

SURFACE MOUNT SILICON DUAL, ISOLATED, OPPOSING ULTRA LOW LEAKAGE SWITCHING DIODE





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# DESCRIPTION:

The CENTRAL SEMICONDUCTOR CMLD6001DO type contains two (2) isolated opposing configuration, silicon switching diodes, manufactured by the epitaxial planar process, epoxy molded in an SOT-563 surface mount package. These devices are designed for switching applications requiring extremely low leakage.

# MARKING CODE: C60

MAXIMUM RATINGS: (T <sub>A</sub> =25°C)	SYMBOL	75	UNITS V		
Continuous Reverse Voltage	V <sub>R</sub>	75	v		
Peak Repetitive Reverse Voltage	V <sub>RRM</sub>	100	V		
Continuous Forward Current	١ <sub>F</sub>	250	mA		
Peak Forward Surge Current, tp=1.0µs	IFSM	4.0	А		
Peak Forward Surge Current, tp=1.0s	IFSM	1.0	А		
Power Dissipation	PD	250	mW		
Operating and Storage Junction Temperature	T <sub>J</sub> , T <sub>stg</sub>	-65 to +150	°C		
Thermal Resistance	ΘJA	500	°C/W		
ELECTRICAL CHARACTERISTICS PER DIODE: (T <sub>A</sub> =25°C unless otherwise noted)					
SYMBOL TEST CONDITIONS	` <sup>С</sup> мін	MAX	UNITS		
I <sub>R</sub> V <sub>R</sub> =75V		500	pА		
BV <sub>R</sub> I <sub>R</sub> =100μA	100		V		
V <sub>F</sub> I <sub>F</sub> =1.0mA		0.85	V		
V <sub>F</sub> I <sub>F</sub> =10mA		0.95	V		

# VF IF=10mA 0.95 V VF IF=100mA 1.1 V CJ VR=0, f=1.0MHz 2.0 pF $t_{rr}$ IR=IF=10mA, Irr=1.0mA, RL=100Ω 3.0 µs

R5 (15-June 2015)



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# SOT-563 CASE - MECHANICAL OUTLINE







#### **PIN CONFIGURATION**



3) Cathode D2 4) Anode D2 5) NC 6) Cathode D1

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DIMENSIONS						
	INCHES		MILLIMETERS			
SYMBOL	MIN	MAX	MIN	MAX		
A	0.0027	0.007	0.07	0.18		
B	0.008		0.20			
C	0.017	0.024	0.45	0.60		
D	0.059	0.067	1.50	1.70		
E	0.020		0.50			
F	0.059	0.067	1.50	1.70		
G	0.043	0.051	1.10	1.30		
Н	0.006	0.012	0.15	0.30		
SOT-563 (REV: R2)						

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## SERVICES

- · Bonded Inventory
- Custom Electrical Screening
- Custom Electrical Characteristic Curves
- SPICE Models
- Custom Packaging
- Package Base Options
- Custom Device Development/Multi Discrete Modules (MDM™)
- Bare Die Available for Hybrid Applications

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R5 (15-June 2015)

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